



NAN YA PLASTICS CORPORATION
 ELECTRONIC MATERIALS DIVISION.
COPPER CLAD LAMINATE DEPARTMENT

**Glass cloth base epoxy resin
 flame retardant copper clad laminate**

NO. 201. TUNG HWA N. ROAD,
 TAIPEI, TAIWAN.

NP-140TL

■ FEATURES

- Multi-functional epoxy renders the material outstanding heat resistance, better dimensional stability, and through-hole reliability that benefit the performance of high layer count multilayer boards.
- HTE copper foil applied to prevent corner cracking.
- High luminance of epoxy contrast with copper for laser type A.O.I.
- UV solder mask may be applied simultaneously in order to increase yields.
- IPC-4101B specification is applicable.

■ PERFORMANCE LIST

Characteristics	Unit	Conditioning	Typical Values	SPEC	Test Method
Volume resistivity	MΩ-cm	C-96/35/90	5.0 x10 ⁹	10 ⁶ ↑	2.5.17
Surface resistivity	MΩ	C-96/35/90	5.0 x10 ⁷	10 ⁴ ↑	2.5.17
Permittivity 1 MHZ	-	C-24/23/50	4.2-4.4	5.4 ↓	2.5.5.9
Permittivity 1 GHZ	-	C-24/23/50	3.8-4.0	-	2.5.5.9
Loss Tangent 1 MHZ	-	C-24/23/50	0.015-0.020	0.035 ↓	2.5.5.9
Loss Tangent 1 GHZ	-	C-24/23/50	0.012-0.014	-	2.5.5.9
Arc resistance	SEC	D-48/50+D-0.5/23	120 ↑	60 ↑	2.5.1
Dielectric breakdown	KV	D-48/50	60 ↑	40 ↑	2.5.6
Moisture absorption	%	D-24/23	0.20-0.30	0.35 ↓	2.6.2.1
Flammability	-	C-24/23/50+E-24/125	94V0	94V0	UL94
Peel strength 1 oz	lb/in	288 x10" solder floating	10-14	6 ↑	2.4.8
Thermal stress	SEC	288 solder dipping	90 ↑	10 ↑	2.4.13.1
Glass transition temp		DSC	140 ± 5	N/A	2.4.25
Dimensional stability X-Y axis	%	E 4/105	0.01-0.03	0.05 ↓	2.4.39
Coefficient of thermal expansion					
Z-axis before Tg	ppm/	TMA	50-70	N/A	2.4.24
Z-axis after Tg	ppm/	TMA	250-350		

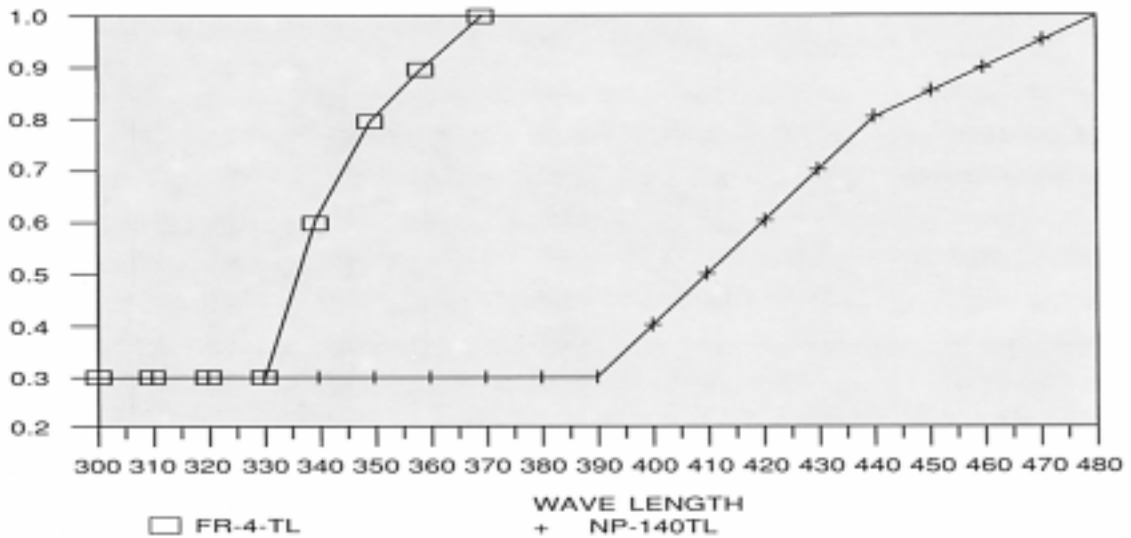
Data shown are nominal values for reference only.

NOTE:

The average value in the table refers to samples of .020" 1/1.

Test method per IPC-TM-650

■ UV TRANSMISSION CURVE OF 0.2mm CCL



■ PRODUCT SIZE & THICKNESS

THICKNESS INCH(mm)	COPPER CLADDING OZ (µm)	SIZE		THICKNESS TOLERANCE
		INCH	mm	
0.004 (0.1)	0.5 (17)	48.8 x 36.6	1240 x 0930	CLASS C/M
to	1.0 (35)	48.8 x 40.5	1240 x 1030	
0.047(1.2)	2.0 (70)	48.8 x 42.5	1240 x 1080	

■ Keeping the core and prepreg in the same grain direction is crucial to ensure the flatness of multilayer boards.

Grain direction is shown on the Certificate of Conformance

■ CERTIFICATION UL

• UL File No. : E98983

■ CONSTRUCTION:

THICKNESS		CONSTRUCTION	THICKNESS		CONSTRUCTION
mm	mil		mm	mil	
0.08	3	2112 1 ply	0.45	18	7628 x 2 + 1080 x 1
0.10	4	1080 2 plies	0.46	18	7667 2 plies
0.11	4	2116 1 ply	0.50	20	7628 3 plies
0.13	5	1080 2 plies	0.53	21	7628 3 plies
0.13sp	5	2116 1 ply	0.60	24	7628 3 plies
0.15	6	1506 1 ply	0.77	31	7628 4 plies
0.16	6	2112 2 plies	0.8	32	7628 4 plies
0.21	8	7628 1 ply	0.9	36	7628 5 plies
0.26	10	2116 2 plies	1.0	39	7628 5 plies
0.30	12	2116 3 plies	1.1	43	7628 6 plies
0.30sp	12	1506 2 plies	1.2	47	7628 6 plies
0.35	14	7628 2 plies			
0.38	15	7628 2 plies			

*1.2,1.1,1.0,0.9,0.77 mm, THICKNESS INCLUDES CLADDING. ALL OTHERS EXCLUDE CLADDING.